

ABSTRACT

An treatment bath for use in the manufacture of copper plated or metallized semiconductor devices and a method of inhibiting corrosion of copper plated or metallized surfaces and circuitry in the semiconductor devices immersed in an aqueous fluid in a treatment bath comprising adding to the aqueous fluid an effective corrosion inhibiting amount of one or more aromatic triazole corrosion inhibitors; fluorometrically monitoring the concentration of aromatic triazole corrosion inhibitors in the aqueous fluid; and adding additional aromatic triazole corrosion inhibitor to the aqueous fluid to maintain an effective corrosion inhibiting concentration of the aromatic triazole corrosion inhibitor in the aqueous fluid.